

## Henkel Adds Thermally Conductive Solution to its Award-Winning Lineup of Technomelt Hot Melt Encapsulants

**Adding another layer of heat transfer improves reliability and long-term performance, and addresses one of today's biggest challenges for electronic products**

**Henkel Adhesive Technologies** recently announced another milestone with the development of a thermally conductive Technomelt material. With the ability to transfer heat through the encapsulating layer, thermally conductive Technomelt products offer dual-function performance in a single material solution.

Technomelt materials are well-recognized as a streamlined alternative to multi-step, messy potting processes. Because Technomelt materials can be melted, molded and cooled quickly under low pressure, they deliver a unique encapsulation technique that provides a high throughput solution for protection of delicate circuitry and PCB assemblies, while forming a self-enclosed housing. These inherent Technomelt advantages are now expanded with the addition of thermal conductivity to enable heat dissipation.

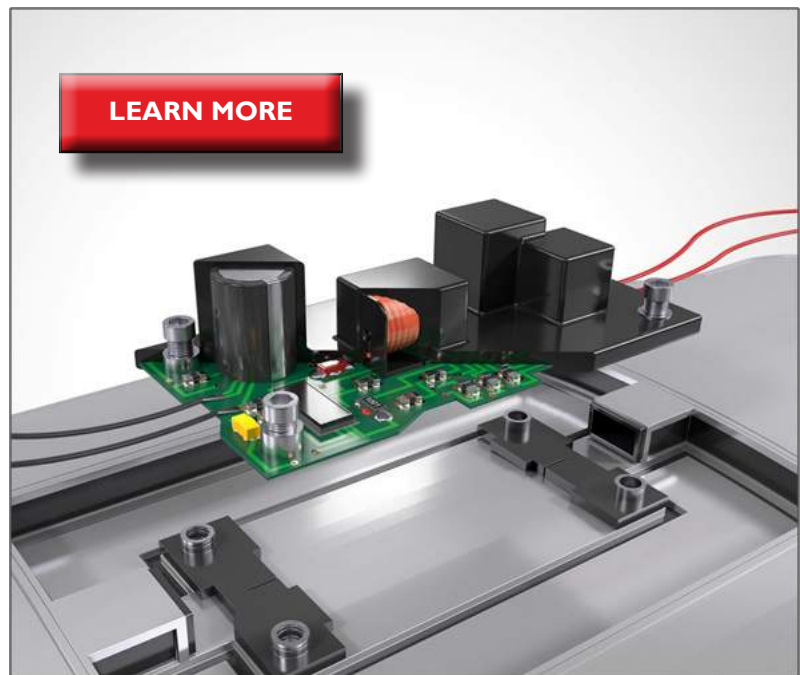
### Applications

- **LED drivers**
- **Power supplies**
- **Solar inverters**
- **Camera modules**
- **Automotive electronic power systems**

### Supporting Data

In testing, the thermally conductive material has shown a 40°C component temperature reduction as compared to standard Technomelt, effectively diffusing heat from its source.

Uniquely formulated for molding techniques, the new Technomelt materials draw on Henkel's broad knowledge of hot melt resin and filler technology to deliver a melt viscosity that is compatible with standard low pressure molding processes and equipment. Filler dispersion is maintained for long periods of time at melt temperatures above 180°C.



**To request samples, pricing or to discuss your thermally conductive application requirements, contact Diverse Electronics at 1-800-388-7308 or [sales@diverseelectronics.com](mailto:sales@diverseelectronics.com).**